

This document explains the function of the Comms, its schematic level design, its board level design, and its functional testing

Comms

In-Orbit Communication
Subsystem Design

Revision: 1.0.2

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1 Introduction

This document explains how the Comms will fulfil the following Functions and conform to the following Requirements. This document refers to the Comms version 1.0, +X Panel version 1.0, and -Z Panel version 1.0.

1.1 Function

The In-Orbit Communication Subsystem (Comms) is responsible for the following:

- Transferring telemetry to the ground station
- Transferring payload data to the ground station
- Transferring commands from the ground station
- Transmitting a locating beacon

1.2 Requirements

The system requirements and Comms design requirements can be found [on GitHub](#).

1.3 Open Systems Interconnection (OSI) Model

The OSI model¹ is a conceptual model that can be applied to any communication system. It has eight layers; each layer serves the layer above it and is served by the layer below it.

1.3.1 Layers

Layer			Protocol Data Unit	Function
Host layers	7	Application	Data	High-level APIs
	6	Presentation		Translation of data between a networking service and an application
	5	Session		Managing communication sessions
	4	Transport	Segment	Reliable transmission of data segments between points on a network
Media layers	3	Network	Packet	Structuring and managing a multi-node network
	2	Data link	Frame	Reliable transmission of data frames between two nodes connected by a physical layer
	1	Physical	Symbol	Transmission and reception of raw bit streams over a physical medium
	0	Medium	Electrons, Photons	The physical medium: copper, fiber, wireless

¹For more information, read [Wikipedia's article](#) on the OSI model

1.3.2 CougSat Communication Subsystem

The communication subsystem, formed from the in-orbit and ground subsystems, fulfills layers 0 through 2 of the OSI model. The Comms serves the Command and Data Handling (C&DH) subsystem which fulfills layers 3 and up. The Ground serves itself for layers 3 and up which results in a graphical representation of the exchanged information. The in-orbit and ground subsystems are very similar as they are required to be compatible. For details on the ground subsystem, see its [design document](#).

1.3.2.1 Layer 0

The communication subsystem is using wireless transmission, in the radio frequency band. There are two bands utilized: 700mm and 230mm. The 700mm radio is the primary radio used for telemetry and beacon. The 230mm radio is the secondary radio used for payload data transfers and only operates in downlink mode.

1.3.2.2 Layer 1

The modulation scheme used is Quadrature Phase Shift Keying (QPSK)². Each symbol is a change in the phase constant of the RF wave. The radios are software defined radios which allows reconfiguration of this layer if necessary. Other modulation schemes can be developed if the hardware supports it.

1.3.2.3 Layer 2

See the Comms μ Controller's [Framing Protocol](#).

1.3.2.4 Layer 3 and Up

See the Ground's [Communication Protocol](#).

1.4 Link Budget

A [link budget](#) for downlink and uplink was tabulated indicating a transmit power of 1W is sufficient for up to 500kbps on the 230mm band. The 700mm band transmitter will incur less losses³ and send slower data⁴ so 1W is also sufficient. Uplink has no problems thanks to access to high gain and high-power transmitters on the ground.

² For more information, read [Wikipedia's article](#) on Phase Shift Keying (PSK)

³ [Free-space path loss](#) is proportional to frequency squared

⁴ A slower data rate has looser requirements for signal-to-noise ratio because there is more time to decode the symbol

2 Detailed Description

This section references the Comms [schematic](#). Page numbers will be listed and may have coordinates listed (number and letter combination found around the frame).

2.1 Functional Block Diagram

The block diagram can be found on the first page of the schematic.

2.1.1 Comms μ Controller

The Comms μ Controller is responsible for interfacing the radio signals and the Command and Data Handling subsystem⁵. This fulfills OSI model⁶ layers 1 and 2. It samples and synthesizes the baseband signals which are mixed with the carrier wave. This constitutes a software defined radio. The μ Controller has non-volatile storage in the form of SPI Flash to store configurations and reference waveforms.

2.1.2 RF Clock Generators

Each radio has a configurable clock generator used to synthesize the carrier waves. For the transmission of the beacon, the generator is the direct source without any modulation to the antenna⁷.

2.1.3 700mm Receiver Radio

Its RF diagram is the top row on page 2. The RF signal from the antenna is connected to the receiver radio via a high isolation RF switch. This switch prevents the transmitter from overdriving the sensitive receiver components and inducing damage. The signal is then amplified by low noise amplifiers which add very little noise to the signal to maintain the highest signal to noise ratio. The signal is then connected to the demodulator which removes the carrier frequency and splits that baseband signal into its in-phase and quadrature-phase signals which are then sampled by the Comms μ Controller and demodulated into binary. The receiver radio is designed for continuous operation and low power⁸.

2.1.4 700mm Transmitter Radio

Its RF diagram is the middle row on page 2. The Comms μ Controller generates in-phase and quadrature-phase baseband signals using its digital to analog converter. This allows arbitrary waveform including voice signals⁹. These signals feed the modulator which puts the baseband signals on the carrier wave. This modulated RF gets amplified with a power amplifier to transmit the desired 1W, see the Link Budget.

⁵ Requirements COMMS-008, COMMS-009

⁶ Open Systems Interconnection (OSI) Model

⁷ Requirements COMMS-001

⁸ Requirement COMMS-005

⁹ Requirement COMMS-006

2.1.5 230mm Transmitter Radio

Its RF diagram is the bottom row on page 2. The Comms μ Controller generates in-phase and quadrature-phase baseband signals using fast GPIO. This only allows each signal to be discrete positive or negative as found in QPSK modulation. If arbitrary waveforms are desired, an external DAC is needed. These signals feed the modulator which puts the baseband signals on the carrier wave. This modulated RF gets amplified with a power amplifier to transmit the desired 1W, see the Link Budget.

2.1.6 5V & 9V Boost Converters

The RF chains require 5V and 9V supplies which come from boost converters. The converters are sourced from the battery rail.

2.2 Schematic

2.2.1 Isolated Grounds

On page 3 of the schematic (D1 & D2), are the six isolated grounds found on the Comms. Power ground (*PGND*) is directly connected to the backplane and the boost converters. Most of the other grounds are shorted to *PGND* using a 0Ω resistor rated up to 2A, the expected current is less than 500mA each. Digital ground (*DGND*) connects to the digital circuitry including the Comms μ Controller. Analog ground (*AGND*) connects to analog circuits including the ADCs, the voltage references, the thermistors, and the operational amplifiers. *AGND* connects to *DGND*. Chassis ground (*CHASSIS*) is connected to the Mechanical Features including bolt holes and the card rails. The 230mm RF chain and the 700 RF chains each have their own RF grounds (*RFGND-0* and *RFGND-1*, respectively).

2.2.2 Power Rails

Page 3 of the schematic illustrates all the power rails on the Comms. Each RF chain can be turned off to save power and as a radio inhibit¹⁰.

2.2.3 Comms μ Controller

The Comms μ Controller (page 4, A3, C1, C2, & C4) is a microcontroller from the STM32 low power family¹¹. It was chosen for its ease of programming, and low power consumption. It needed fast ADCs and DACs for sampling and synthesizing the baseband signals.

The μ Controller's reset pin is connected to the backplane such that if it or any subsystem needs to reset itself, all the subsystems reset. This is to put all the subsystems in a known state which reduces cause for error.

2.2.3.1 Programming Connections

During testing, the Comms μ Controller is programmed via Serial Wire Debug¹² (SWD, page 4, A1). The process of programming is made simple with just a

¹⁰ Requirement REQ-005

¹¹ [STM32L476RG](#)

¹² For more information, see [ARM's article](#) on SWD

single six pin header and a robust software utility. In orbit, the μ Controller can be programmed via JTAG¹³. The [In-Flight JTAG Reprogrammer](#) (IFJR) connects via the backplane, through tri-state buffers/logic level converters¹⁴ (page 4, C1:D2). The IFJR can enable or disable the tri-state buffer which essentially disconnects the JTAG interface from the Comms μ Controller (it outputs high impedance), allowing the SWD to program. The logic level conversion feature is not used.

2.2.4 I²C Bus

The Comms μ Controller has one I²C bus (page 4, C4). It connects to the monitoring ADCs.

2.2.4.1 ADCs

There are 3 ADCs¹⁵ connected to the Comms μ Controller, each with 16 single-ended inputs or eight differential inputs or a combination. The ADC was chosen for its low power, differential inputs, small package, and up to 27 addresses. The list of address follow:

- [0xEE] Global ADC address
- [0x28] ADC-0 (page 10, A2), voltage and current
- [0x2A] ADC-1 (page 10, A4), voltage and current
- [0x2E] ADC-2 (page 10, C2), voltage and current

The ADCs' mux output and ADC input have voltage dividers (page 10, B2, B4, & D2) that reduces the voltage of every input to place their level within the sensing range. Using paired resistors helps match the source impedance to the ADC across temperature. A mismatch results in an offset. The input range is $\frac{V_{ref}}{2} * \frac{25k\Omega}{5k\Omega} = 4.5V$ but is limited by the IC's ESD diodes¹⁶ to the supply rail of 3.3V. To allow even high input voltages, those nets have series resistors (page 10, C1 & C3). With $20k\Omega$, $V = 3.3V * \frac{45k\Omega}{25k\Omega} = 5.9V$. With $50k\Omega$, $V = 3.3V * \frac{75k\Omega}{25k\Omega} = 9.9V$.

2.2.5 SPI Bus

The Comms μ Controller has three SPI buses¹⁷. One connects to the C&DH to transfer packets and telemetry. One connects to the RF Clock Generators. One connects to the μ SD cards.

2.2.5.1 Backplane to the C&DH

The Comms μ Controller is a slave to the C&DH, see the [interface document](#) for details.

¹³ For more information, see [Wikipedia's article](#) on JTAG

¹⁴ [TXS0102](#)

¹⁵ [LTC2499](#)

¹⁶ ESD diodes are reversed biased diodes between every pin and VCC and GND. When a pin is above VCC or below GND, these diodes conduct. The intent is to prevent ESD transients from harming the device, they are not designed for continuous conduction

¹⁷ For more information, see [Wikipedia's article](#) on SPI

2.2.5.2 RF Clock Generators

The Comms μ Controller is a transmit only master to the RF Clock Generators. Each generator has a tri-state buffer (page 8, A2, & C2; page 9, B2) which only connects the bus if the generator's rail is on. Without this, when the generator is turned off, its ESD diodes would prevent the bus from moving above *GND* effectively disabling the bus.

2.2.5.3 SPI Flash

The Comms μ Controller is a master to two SPI Flash chips¹⁸ (page 15) that provides 16Mb of mirrored storage or 32Mb of striped storage.

2.2.6 Current Monitoring

At various locations, the power chain has shunt resistors connected to ADCs in differential mode to monitor the current. Those locations are:

- 5V Regulator output (page 6, B6)
- 9V Regulator output (page 6, C6)
- Each RF chain input (page 7)

2.2.7 Voltage Monitoring

At various locations, the power chain is probed for the voltage using the ADCs in single ended mode. Those locations are:

- 5V Regulator output (page 6, B6)
- 9V Regulator output (page 6, C6)

2.2.8 Temperature Monitoring

At various locations, the temperature is monitored using thermistors and the ADCs in single ended mode. Those locations are:

- 5V Regulator (page 6, A3)
- 9V Regulator (page 6, C3)
- Comms μ Controller (page 4, B4)
- RF clock generators (page 8, A4, C4; page 9, B4)
- 230mm downlink RF chain (page 11, B3, B5, & D4)
- 700mm downlink RF chain (page 12, B3, B5, & D5)
- 700mm uplink RF chain (page 13, B4 & C4; page 14, C4)

2.2.9 Analog Voltage Reference and Supply

The Comms has a precision voltage reference¹⁹ (page 5, B6) for calibrating the ADCs. This is inputted into the ADCs' reference input.

The Comms has an analog voltage supply (page 5, C6) which is fed by the 3.3V rail filtered with a ferrite bead and capacitors. Precision is not required as all ADCs use the precision voltage reference for calibration. This is the source for the Temperature Monitoring thermistors and operational amplifiers. A negative

¹⁸ [IS25LP016D](#)

¹⁹ [MCP1501](#)

voltage supply²⁰ for the op-amps takes the 3.3V rail and inverts it (page 10, C4:C6) to supply the op-amps' negative supply.

2.2.10 5.0V Regulation

The 5.0V regulator (page 6, B1:B6) is switching mode, boost topology. The converter²¹ automatically senses the output voltage and adjusts the switching parameters to keep the output at 5.0V. The converter has an integrated switching MOSFET. The converter was chosen for its small size and high efficiency. The output voltage is tuned to 5.1V to allow enough head room for the 5.0V Low Drop-Out Regulators to properly regulate.

The large package Multi-Layer Ceramic Capacitors (MLCC, input and output filtering) are placed in series such that one was to fail short, they would not compromise the power chain. The small package and tantalum capacitors are not likely to fail due to mechanical vibration.

The converter and inductor (page 6, B2:B3) are thermally connected to a thermistor for Temperature Monitoring and an optional heatsink if a thermal test indicates they need additional heat dissipation.

2.2.11 9.0V Regulation

The 9.0V regulator (page 6, C1:C6) is switching mode, boost topology. The converter²² automatically senses the output voltage and adjusts the switching parameters to keep the output at 9.0V. The converter has an integrated switching MOSFET. The converter was chosen for its small size and high efficiency.

The large package Multi-Layer Ceramic Capacitors (MLCC, input and output filtering) are placed in series such that one was to fail short, they would not compromise the power chain. The small package and tantalum capacitors are not likely to fail due to mechanical vibration.

The converter and inductor (page 6, C2:C3) are thermally connected to a thermistor for Temperature Monitoring and an optional heatsink if a thermal test indicates they need additional heat dissipation.

2.2.12 Low Drop-Out Regulators

The sensitive RF components are supplied through low drop-out (LDO) regulators²³ (page 7, B2, B4, B6, C2, C4, & C6). These are linear regulators that require a small drop-out²⁴ for proper regulation. They are used to reject the switching noise from the switching mode power supplies. The "3.3V" LDO regulators are might require the Electrical Power Subsystem to tune its 3.3V regulator to a higher voltage to allow enough head room for proper regulation.

²⁰ [LM2776](#) and [TPS732](#)

²¹ [TPS61236](#)

²² [TPS61089](#)

²³ [TPS73250](#) and [LP5907](#)

²⁴ Voltage difference between input and output

2.2.13 RF Clock Generators

The RF Clock Generators²⁵ (page 8, A3, & C3; page 9, B3) have a voltage-controlled oscillator and a phase-locked loop to take a reference clock and synthesize a RF wave. The reference clocks²⁶ (page 8, A3, & C3; page 9, C3) have high frequency stability and are supplied with ferrite beads to further increase frequency stability. The supporting circuitry for the generators was created using Analog Device's [ADIsimPLL](#). The design files can be found under the [documentation folder](#). The output of the generators is designed to drive a 50Ω load.

The 700mm Receiver Radio's demodulator divides its clock input by two, so the RF clock generator needs to output double the carrier frequency.

2.2.14 Differential Drivers

The Comms μ Controller outputs its basebands signals 0 to 3.3V single ended. The modulators' baseband signals are differential with a different amplitude. The differential output op-amps²⁷ (page 10, A1:D3) are used to perform this translation. The μ Controller input is subtracted from a 1.65V reference (page 10, A4:A6) then multiplied by the proper gain to have the 3.3V_{pp} signal reduced to 1.0V_{pp} or 0.6V_{pp} as the modulator desires. This signal is then added to the proper common mode voltage reference (page 10, B4:B6, C4:C6). This circuit was simulated in [LTSpice](#) and can be found under [electrical design](#). Precision resistors are used to reduce any common mode offset or gain imbalance.

2.2.15 RF Modulators

The 700mm Transmitter Radio's modulator (page 12, B3) and the 230mm Transmitter Radio's modulator (page 11, B3) have the RF Clock Generators AC coupled into their local oscillator input, and the Differential Drivers are directly connected to the baseband inputs. The RF output is AC coupled to the next element in the RF chain.

2.2.16 RF Demodulator

The 700mm Receiver Radio's demodulator (page 14, B3:B4) has the RF Clock Generators AC coupled into its local oscillator input. The 60.4 Ω termination resistor is used to match a 50 Ω input into the demodulator. The RF signal is connected to the modulator's input through a 1:4 balun (page 13, B2) to match a 50 Ω input into the demodulator. The gain of the demodulator is set by a voltage divider (page 14, B2) which is initially set to maximum gain.

The demodulator outputs differential baseband signals 1.0V \pm 500mV. this amplified and translated to 1.65V \pm 1V single ended for input to the Comms

²⁵ [ADF4360](#)

²⁶ [ECS-TXO-3225](#)

²⁷ [AD8137](#)

μ Controller's ADC by op-amps²⁸ (page 13, C2 & C5). This circuit was simulated in LTSpice and can be found under [electrical design](#).

2.2.17 Low Noise Amplifier

The low noise amplifiers (LNA)²⁹ (page 11, B5; page 12, B5; page 13, B3 & C3) amplify the RF signal for the next component in the RF chain. They were chosen for their low noise figure, broadband response, and high gain. The gain is set by the bias voltage and is $19dB$. For the 700mm Receiver Radio's LNAs, the bias voltage can be shorted to ground which disables the amplifier. This is required, along with toggling the RF switch, when transmitting on 700mm to not damage the demodulator. The output is biased via a ferrite bead to provide power yet decouple the RF signal from the power supply. The output is AC coupled to feed into the next component.

2.2.18 Power Amplifiers

The power amplifiers³⁰ (page 10, C4; page 11, C4) are the final amplifiers for the RF signal. They drive the antennas and output the desired $1W$, see the Link Budget. They were chosen for the output power, linearity, and broadband response. The gain is set by the bias voltage of -4 to $0V$. The Comms μ Controller outputs a PWM signal which is filtered and inverted to achieve an adjustable range of $-3.3V$ to $0V$. This is achieved by op-amps³¹. This circuit was simulated in LTSpice and can be found under [electrical design](#). The output is biased via an inductor to provide power yet decouple the RF signal from the power supply. The output is AC coupled to feed into the antennae.

2.2.19 Mechanical Features

The 5V & 9V Boost Converters heatsink (page 6, D1:D2) and RF chain heatsinks (page 11, D1; page 12, A1) mount directly to the Comms board using bolts. These holes are conductive and connected directly to *CHASSIS*, see Isolated Grounds. The Comms also slots into the structure using rails³² which are also conductive and connected directly to *CHASSIS*. Each of the holes have a capacitor and resistor connecting to power ground which will absorb and dissipate transients.

2.3 Board

The board shall also conform to the dimensions specified by the [CougSat Module Standard](#).

²⁸ [AD8515](#)

²⁹ [MAAP-011229](#)

³⁰ [MAAP-011232](#)

³¹ [AD8515](#)

³² See [backplane documentation](#) for details

2.3.1 Layer Stack-Up

The board shall be four layered with ENIG finish, see Figure 1. Only through vias shall be used. The external copper weight shall be $35\mu m$ and the internal copper weight shall be $18\mu m$.

Layer	Thickness	Primary Function
1 (top)	$35\mu m$ (1oz)	SMD components, RF & signal traces
Prepreg	$200\mu m$	
2	$18\mu m$ (0.5oz)	Ground planes
Core	$500\mu m$	
3	$18\mu m$ (0.5oz)	Power planes
Prepreg	$200\mu m$	
4 (bottom)	$35\mu m$ (1oz)	Signal traces

Figure 1: Stack-Up

2.3.2 Layout Constraints

Unless specified in the following subsections, all signals shall use the default parameters below. Signals in the following subsections do not include their sense signals unless otherwise specified. Trace width can be broken if a trace needs to bottleneck down to a pin, the bottleneck shall be minimized.

Trace width:	$0.16mm$
Vias:	$\varnothing 0.3mm$, unlimited count
Separation:	$0.16mm$
Length:	unlimited

Devices with specific placement and routing considerations are called out on the schematic, see "CAD Note:"

2.3.2.1 All 50Ω Impedance Traces

This applies to all RF traces except the demodulator's RF input. These traces shall be a coplanar waveguide with ground³³.

Trace width:	$0.35mm$
Gap width:	$0.16mm$
Vias:	none
Length:	minimize

2.3.2.2 All 200Ω Impedance Traces

This applies to the demodulator's RF input. These traces shall be an edge coupled microstrip³⁴ with differential impedance of 200Ω . Ground located on second layer below ($0.8mm$ substrate thickness).

Trace width:	$0.16mm$
Gap width:	$0.4mm$
Vias:	none
Length:	minimize

³³ For more information, read [Microwaves101's article](#) on CPW

³⁴ For more information, see [Microwaves101's article](#) on microstrips

2.3.2.3 All Differential Signals

This applies to the modulators' inputs. Single ended to/from differential shall occur as close to the single ended side as possible.

Trace width:	0.16mm
Gap width:	0.16mm
Length:	Length match $\pm 1.0mm$
Vias:	minimize

2.3.2.4 Regulator Inputs - VBATT, PGND

This applies to *VBATT* and *PGND* between the backplane and the inputs to the regulators and their input capacitors.

Trace width:	1.0mm (2.0mm on internal layers)
--------------	----------------------------------

2.3.2.5 Regulator Outputs - 5.0V, 9.0V, PGND

PGND applies to between the regulators, their output capacitors, and the backplane.

Trace width:	0.5mm (1.0mm on internal layers)
--------------	----------------------------------

2.3.2.6 Regulator Channels - 3.3V_[0:3], 5.0V_[0:3], 9.0V_[0:1], PGND

PGND applies to between the regulators, their loads, and the backplane.

Trace width:	0.5mm (1.0mm on internal layers)
--------------	----------------------------------

2.3.2.7 SPI Buses - SPL_[SCK, MOSI, MISO, CS], RFCLK_[SCK, MOSI, CS], COM_SPL_[SCK, MOSI, MISO, CS]

Length:	Each node shall be length matched $\pm 1.0mm$
Stubs:	< 10.0mm

2.3.2.8 JTAG - JTAG_[TCK, TDI, TDO, TMS], BUS_JTAG_[TCK, TDI, TDO, TMS]

Length:	Each node shall be length matched $\pm 1.0mm$
Stubs:	< 10.0mm

2.3.2.9 I²C - I2C_[SCL, SDA]

Length:	Each node shall be length matched $\pm 1.0mm$
Stubs:	< 10.0mm

3 Testing

All tests shall be performed at room temperature and not under vacuum unless otherwise specified. If any modifications are performed, take note. Include enough information to understand circuit behavior and for others to replicate the results. Include any software written to execute the test and link it in the test notes section. Save all software, waveforms, etc. in a subfolder of the board's test folder for each test³⁵.

- Waveforms shall be captured whenever appropriate
- Have the event take fill the screen (for fast events, zoom in; for slow events, zoom out)
- Label each channel accurately
- Only have bandwidth limiting if necessary for the test (this applies to the oscilloscope and probe settings)
- If ringing or overshoot occurs, use a ground spring or differential probe

Results location: <https://github.com/CougsInSpace/CougSat1-Hardware/tree/master/CougSat1-PowerBoard/Testing/Comms.1.0>

Common test instructions can be found on the [wiki](#).

3.1 Before First Power-On Check

This test is required to be executed before any external power is applied to the Comms.

3.1.1 Test Instructions

Measure the resistance of various points in reference to *PGND* located at the backplane. Measure the resistance across each current shunt resistor. This is informational only; the resistance of the current shunt resistor is used to calibrate the Current Monitoring.

3.1.2 Test Data

Node	Resistance		Node	Resistance
VBATT			3.3V	
3.3V-0			3.3V-1	
3.3V-2			5.0V	
5.0V-0			5.0V-1	
5.0V-2			9.0V	
9.0V-0			9.0V-1	
I2C_SCL			I2C_SDA	

Net	Resistor	Value		Net	Resistor	Value
3.3V-0	R4			3.3V-1	R113	
3.3V-2	R37			5.0V Output	R1	
5.0V-0	R5			5.0V-1	R114	
5.0V-2	R38			9.0V Output	R15	

³⁵ For test 3.1, place files in the subfolder "3.1" and so on

Net	Resistor	Value		Net	Resistor	Value
9.0V-0	R27			9.0V-1	R39	

3.1.3 Test Notes

Delete me if no notes are required.

3.2 Power Rail Switching

Results: Pass / Fail

This test evaluates the circuit described in Power Rails.

3.2.1 Test Instructions

Hold the μ Controller in reset or program a blank image, verify the power rails are powered off. Have the μ Controller enable the power rail, verify the power rails are powered on, ensuring the rail turns on only with its control signal.

3.2.2 Test Data

Hold the μ Controller in reset, measure the voltage of each power rail			
Rail	Voltage	Passing Criteria	Pass / Fail
3.3V-0		Voltage < 50mV	
3.3V-1		Voltage < 50mV	
3.3V-2		Voltage < 50mV	
5.0V-0		Voltage < 50mV	
5.0V-1		Voltage < 50mV	
5.0V-2		Voltage < 50mV	
9.0V-0		Voltage < 50mV	
9.0V-1		Voltage < 50mV	

Have the μ Controller enable the power rail, measure the voltage of each power rail. Ensure the rail turns on only with its control signal				
Rail	Control Signal	Voltage	Passing Criteria	Pass / Fail
3.3V-0	PC_LDO_3.3V		Voltage > 3V	
3.3V-1	PC_LDO_3.3V		Voltage > 3V	
3.3V-2	PC_LDO_3.3V		Voltage > 3V	
5.0V-0	PC_MOD_230		Voltage > 4V	
5.0V-1	PC_MOD_700		Voltage > 4V	
5.0V-2	PC_DEMOD		Voltage > 4V	
9.0V-0	PC_MOD_230		Voltage > 8V	
9.0V-1	PC_MOD_700		Voltage > 8V	

3.2.3 Test Notes

Delete me if no notes are required.

3.3 I²C Bus

Results: Pass / Fail

This test evaluates the circuit described in I²C Bus.

3.3.1 Test Instructions

At the pull up resistors of the I²C bus, validate the following timing parameters, see Test Data table for the valid range for each parameter. Refer to Figure 2 for a definition of the timing parameters.

- V_H Logic high level
- V_L Logic low level
- f_{SDA} Clock frequency
- $t_{HD(SDA)}$ Hold time for (repeated) start condition
- t_{LOW} Low period of *SCL*
- t_{HIGH} High period of *SCL*
- $t_{SU(STA)}$ Setup time for a repeated start condition
- $t_{HD(SDA)}$ Data hold time
- $t_{SU(SDA)}$ Data setup time
- t_r Rise time for *SDA*
- t_f Fall time for *SDA*
- $t_{SU(STO)}$ Setup time for stop condition
- t_{BUF} Bus free time between a second start condition

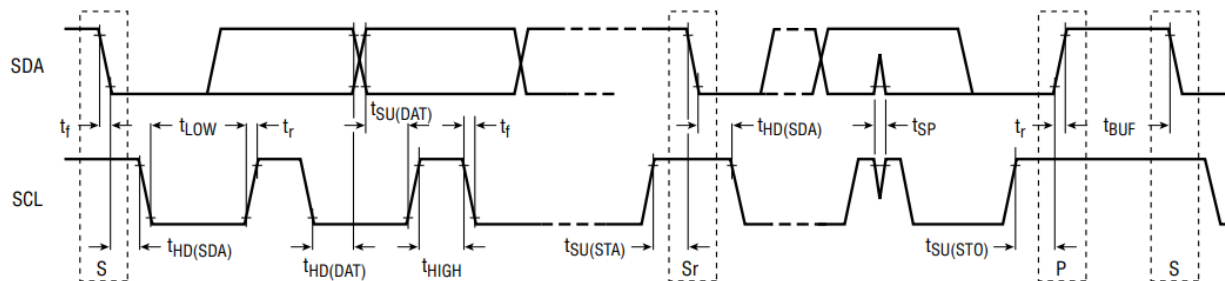


Figure 2: Definition of timing parameters for Fast mode on the I²C bus

Note: The μ Controller should generate random I²C traffic on the bus.

3.3.2 Test Data

At the pull up resistors of the I ² C bus, validate the following timing parameters				
Symbol	Capture the <i>SDA</i> and <i>SCL</i> lines	Value	Passing Criteria	Pass / Fail
V_H			$V > 2.45V$	
V_L			$V < 990mV$	
f_{SDA}			$f < 400kHz$	
$t_{HD(SDA)}$			$t > 600ns$	
t_{LOW}			$t > 1.3\mu s$	
t_{HIGH}			$t > 600ns$	
$t_{SU(STA)}$			$t > 600ns$	
$t_{HD(SDA)}$			$0 < t < 900ns$	
$t_{SU(SDA)}$			$t > 600ns$	
t_r			$30ns < t < 300ns$	
t_f			$30ns < t < 300ns$	

At the pull up resistors of the I^2C bus, validate the following timing parameters				
Symbol	Capture the SDA and SCL lines	Value	Passing Criteria	Pass / Fail
$t_{SU(STO)}$			$t > 600ns$	
t_{BUF}			$t > 1.3\mu s$	

3.3.3 Test Notes

Delete me if no notes are required.

3.4 SPI Bus

Results: Pass / Fail

This test evaluates the circuit described in SPI Bus.

3.4.1 Test Instructions

At the end (furthest away from the μ Controller) of each SPI bus, validate the following timing parameters, see Test Data table for the valid range for each parameter.

- V_H Logic high level
- V_L Logic low level
- f_{SCK} Clock frequency
- t_{LOW} Low period of SCK
- t_{HIGH} High period of SCK
- $t_{HD(CS)}$ Data hold time of CS
- $t_{SU(CS)}$ Data setup time of CS
- $t_{HD(MOSI)}$ Data hold time of $MOSI$
- $t_{SU(MOSI)}$ Data setup time of $MOSI$

Note: The μ Controller should generate random SPI traffic on the bus.

3.4.2 Test Data

At the backplane end of the COM_SPI bus, validate the following timing parameters				
Symbol	Capture the SCK , $MOSI$, and CS lines	Value	Passing Criteria	Pass / Fail
V_H			$V > 2.30V$	
V_L			$V < 990mV$	
f_{SCK}			$f < 20MHz$	
t_{LOW}			$t > 25ns$	
t_{HIGH}			$t > 25ns$	
$t_{HD(CS)}$			$t > 20ns$	
$t_{SU(CS)}$			$t > 20ns$	
$t_{HD(MOSI)}$			$t > 10ns$	
$t_{SU(MOSI)}$			$t > 10ns$	

At the U8 end of the SPI bus, validate the following timing parameters				
Symbol	Capture the <i>SCK</i> , <i>MOSI</i> , and <i>CS</i> lines	Value	Passing Criteria	Pass / Fail
V_H			$V > 2.30V$	
V_L			$V < 990mV$	
f_{SCK}			$f < 20MHz$	
t_{LOW}			$t > 25ns$	
t_{HIGH}			$t > 25ns$	
$t_{HD}(CS0)$			$t > 20ns$	
$t_{SU}(CS0)$			$t > 20ns$	
$t_{HD}(MOSI)$			$t > 10ns$	
$t_{SU}(MOSI)$			$t > 10ns$	

At the U36 end of the RFCLK bus, validate the following timing parameters				
Symbol	Capture the <i>SCK</i> , <i>MOSI</i> , and <i>CS</i> lines	Value	Passing Criteria	Pass / Fail
V_H			$V > 1.5V$	
V_L			$V < 600mV$	
f_{SCK}			$f < 20MHz$	
t_{LOW}			$t > 25ns$	
t_{HIGH}			$t > 25ns$	
$t_{HD}(CS)$			$t > 20ns$	
$t_{SU}(CS)$			$t > 20ns$	
$t_{HD}(MOSI)$			$t > 10ns$	
$t_{SU}(MOSI)$			$t > 10ns$	

3.4.3 Test Notes

Delete me if no notes are required.

3.5 Current Monitoring

Results: Pass / Fail

This test evaluates the circuit described in Current Monitoring.

3.5.1 Test Instructions

Apply a 10mA to 250mA resistive load to a 9.0V-0. Compare the current measured by the Comms and a DMM.

Note: $Error = \frac{|I_{Comms} - I_{DMM}|}{I_{DMM}}$

3.5.2 Test Data

Apply a 10mA to 250mA resistive load to a single output channel. Compare the current measured by the Comms and a DMM					
Load	EPS Current	DMM Current	Error	Passing Criteria	Pass / Fail
10mA				$Error < 1.0\%$	
25mA				$Error < 1.0\%$	

Apply a 10mA to 250mA resistive load to a single output channel. Compare the current measured by the Comms and a DMM					
Load	EPS Current	DMM Current	Error	Passing Criteria	Pass / Fail
50mA				<i>Error < 1.0%</i>	
100mA				<i>Error < 1.0%</i>	
250mA				<i>Error < 1.0%</i>	

3.5.3 Test Notes

Delete me if no notes are required.

3.6 Voltage Monitoring

Results: Pass / Fail

This test evaluates the circuit described in Voltage Monitoring.

3.6.1 Test Instructions

Compare the voltage measured by the Comms and a DMM on the following signals:

- *L3.3V-0N*
- *L3.3V-1P*
- *5.0V*

Note: $Error = \frac{|V_{Comms} - V_{DMM}|}{V_{DMM}}$

3.6.2 Test Data

Compare the voltage measured by the Comms and a DMM					
Signal	Comms Voltage	DMM Voltage	Error	Passing Criteria	Pass / Fail
<i>L3.3V-0N</i>				<i>Error < 1.0%</i>	
<i>L3.3V-1P</i>				<i>Error < 1.0%</i>	
<i>5.0V</i>				<i>Error < 1.0%</i>	

3.6.3 Test Notes

Delete me if no notes are required.

3.7 Temperature Monitoring

Results: Pass / Fail

This test evaluates the circuit described in Temperature Monitoring.

3.7.1 Test Instructions

Compare the temperature measured by the Comms and a thermometer on the following temperature sensors:

- 5.0V Regulator
- μ Controller
- +X+Y

Note: $Error = |T_{Comms} - T_{THERMOMETER}|$

3.7.2 Test Data

Compare the temperature measured by the Comms and a thermometer					
Sensor	Comms Temperature	Thermometer Temperature	Error	Passing Criteria	Pass / Fail
5.0V Regulator				$Error < 2^{\circ}C$	
μ Controller				$Error < 2^{\circ}C$	
+X+Y				$Error < 2^{\circ}C$	

3.7.3 Test Notes

Delete me if no notes are required.

3.8 Analog Voltage Reference

Results: Pass / Fail

This test evaluates the circuit described in Analog Voltage Reference and Supply and Differential Drivers. More information on measuring noise/ripple as well as using an oscilloscope can be found on the Electrical Systems Team page of the Wiki under Tutorials and Resources.

3.8.1 Voltage

3.8.1.1 Test Instructions

Measure the voltage of the following signals:

- $AVREF$
- $VREF_CM_IN$
- $VREF_CM_OUT_230$
- $VREF_CM_OUT_700$

Note: Measure the DC component with $f < 0.1Hz$

3.8.1.2 Test Data

Measure the voltage of the following signals			
Signal	Voltage	Passing Criteria	Pass / Fail
AVREF		$1.7982V < V < 1.8018V$	
VREF_CM_IN		$1.635V < V < 1.665V$	
VREF_CM_OUT_300		$1.215V < V < 1.225V$	
VREF_CM_OUT_700		$0.695V < V < 0.705V$	

3.8.1.3 Test Notes

Delete me if no notes are required.

3.8.2 Ripple

3.8.2.1 Test Instructions

Measure the ripple of the following signals:

- $AVREF$

- $V_{REF_CM_IN}$
- $V_{REF_CM_OUT_230}$
- $V_{REF_CM_OUT_700}$

Note: Measure the AC component with $0.1\text{Hz} < f < 100\text{Hz}$

3.8.2.2 Test Data

Measure the voltage ripple of the following signals				
Signal	Capture the Ripple	Voltage	Passing Criteria	Pass / Fail
AVREF			$ V_{ripple} < 180\mu V$	
$V_{REF_CM_IN}$			$ V_{ripple} < 16nV$	
$V_{REF_CM_OUT_300}$			$ V_{ripple} < 12nV$	
$V_{REF_CM_OUT_700}$			$ V_{ripple} < 7nV$	

3.8.2.3 Test Notes

Delete me if no notes are required.

3.8.3 Noise

3.8.3.1 Test Instructions

Measure the noise of the following signals:

- AV_{REF}
- $V_{REF_CM_IN}$
- $V_{REF_CM_OUT_230}$
- $V_{REF_CM_OUT_700}$

Note: Measure the AC component with $100\text{Hz} < f$

3.8.3.2 Test Data

Measure the voltage noise of the following signals				
Signal	Capture the Ripple	Voltage	Passing Criteria	Pass / Fail
AVREF			$ V_{noise} < 90\mu V$	
$V_{REF_CM_IN}$			$ V_{noise} < 8nV$	
$V_{REF_CM_OUT_300}$			$ V_{noise} < 6nV$	
$V_{REF_CM_OUT_700}$			$ V_{noise} < 3nV$	

3.8.3.3 Test Notes

Delete me if no notes are required.

3.9 μ Controller Programming

Results: Pass / Fail

This test evaluates the circuit described in Programming Connections.

3.9.1 Test Instructions

Connect a SWD programmer to the SWD header and upload an image, validate the μ Controller is properly programmed. Connect a JTAG programmer to the backplane and upload an image, validate the μ Controller is properly programmed.

Note: Follow the programming instructions on the [wiki](#).

3.9.2 Test Data

Program the μ Controller via SWD and JTAG, validate the μ Controller is properly programmed		
Programmer	Passing Criteria	Pass / Fail
SWD	μ Controller properly programmed	
JTAG	μ Controller properly programmed	

3.9.3 Test Notes

Delete me if no notes are required.

3.10 5.0V and 9.0V Regulator

Results: Pass / Fail

This test evaluates the circuit described in 5.0V Regulation and 9.0V Regulation. More information on measuring noise/ripple as well as using an oscilloscope can be found on the Electrical Systems Team page of the Wiki under Tutorials and Resources

3.10.1 Output Voltage

3.10.1.1 Test Instructions

Apply 3.7V to VBATT. Measure the voltage of the 5.0V and 9.0V regulators under no load and under a 200mA resistive load.

Note: Measure the DC component with $f < 0.1\text{Hz}$

3.10.1.2 Test Data

Measure the voltage of the 5.0V and 9.0V regulators under no load and under a 200mA resistive load				
Regulator	No Load Voltage	200mA Load Voltage	Passing Criteria	Pass / Fail
5.0V			$5.05V < V < 5.25V$	
9.0V			$8.55V < V < 9.45V$	

3.10.1.3 Test Notes

Delete me if no notes are required.

3.10.2 Output Ripple

3.10.2.1 Test Instructions

Apply 3.7V to VBATT. Measure the ripple of the 5.0V and 9.0V regulators whilst under a 200mA resistive load.

Note: Measure the AC component with $0.1\text{Hz} < f < 100\text{Hz}$

3.10.2.2 Test Data

Measure the ripple of the 5.0V and 9.0V regulators whilst under a 200mA resistive load.			
Regulator	Capture the ripple	Passing Criteria	Pass / Fail
5.0V		$ V_{\text{ripple}} < 25\text{mV}$	
9.0V		$ V_{\text{ripple}} < 45\text{mV}$	

3.10.2.3 Test Notes

Delete me if no notes are required.

3.10.3 Output Noise

3.10.3.1 Test Instructions

Apply 3.7V to VBATT. Measure the noise of the 5.0V and 9.0V regulators whilst under a 200mA resistive load. Measure at the test point; if the noise is too excessive, measure across the output capacitor.

Note: Measure the AC component with $100\text{Hz} < f$

3.10.3.2 Test Data

Measure the noise of the 5.0V and 9.0V regulators whilst under a 200mA resistive load.			
Regulator	Capture the noise	Passing Criteria	Pass / Fail
5.0V		$ V_{\text{noise}} < 50\text{mV}$	
9.0V		$ V_{\text{noise}} < 90\text{mV}$	

3.10.3.3 Test Notes

Delete me if no notes are required.

3.10.4 Output Efficiency

3.10.4.1 Test Instructions

Measure the efficiency of the 5.0V and 9.0V regulators whilst under a 10mA to 200mA resistive loads and with 3.3V to 4.1V input voltage on VBATT.

Note: $\text{Efficiency} = \frac{P_{\text{out}}}{P_{\text{in}}}$, measure the power across the input and output current shunt resistors.

3.10.4.2 Test Data - 5.0V

Measure the efficiency of the 5.0V regulator whilst under a 10mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 5.0V regulator whilst under a 20mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 5.0V regulator whilst under a 50mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 5.0V regulator whilst under a 100mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 70%</i>	
3.7V				<i>Efficiency > 70%</i>	
4.1V				<i>Efficiency > 70%</i>	

Measure the efficiency of the 5.0V regulator whilst under a 200mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 90%</i>	
3.7V				<i>Efficiency > 90%</i>	
4.1V				<i>Efficiency > 90%</i>	

3.10.4.3 Test Data - 9.0V

Measure the efficiency of the 9.0V regulator whilst under a 10mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 9.0V regulator whilst under a 20mA resistive load and 3.3V to 4.1V input voltage.					
Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 9.0V regulator whilst under a 20mA resistive load and 3.3V to 4.1V input voltage.

Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 9.0V regulator whilst under a 50mA resistive load and 3.3V to 4.1V input voltage.

Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 50%</i>	
3.7V				<i>Efficiency > 50%</i>	
4.1V				<i>Efficiency > 50%</i>	

Measure the efficiency of the 9.0V regulator whilst under a 100mA resistive load and 3.3V to 4.1V input voltage.

Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 80%</i>	
3.7V				<i>Efficiency > 80%</i>	
4.1V				<i>Efficiency > 80%</i>	

Measure the efficiency of the 9.0V regulator whilst under a 200mA resistive load and 3.3V to 4.1V input voltage.

Input Voltage	Power In	Power Out	Efficiency	Passing Criteria	Pass / Fail
3.3V				<i>Efficiency > 90%</i>	
3.7V				<i>Efficiency > 90%</i>	
4.1V				<i>Efficiency > 90%</i>	

3.10.4.4 Efficiency Plot

Create a plot of current versus efficiency with each input voltage.

3.10.4.5 Test Notes

Delete me if no notes are required.

3.10.5 Current Limit

3.10.5.1 Test Instructions

Apply 3.7V to VBATT. For each regulator, apply an increasing load to its output until the current no longer increases. Measure voltage and current of the rail.

Note: The load will likely be increased by adding more resistors in parallel or decrease the load resistance.

3.10.5.2 Test Data

Apply an increasing load to 3.3V outputs until the current no longer increases			
Regulator	Max Current	Passing Criteria	Pass / Fail
5.0V		$500mA < I < 1A$	
9.0V		$500mA < I < 1A$	

3.10.5.3 Test Notes

Delete me if no notes are required.

3.10.6 Load Response

3.10.6.1 Test Instructions

Apply 3.7V to VBATT. Apply the following loads to the both regulator outputs:

- No load to 200mA resistive load
- 200mA resistive load to no load
- No load to 10 μ F MLCC
- 200mA resistive load adding 10 μ F MLCC
- No load to short circuit
- Short circuit to no load
- 200mA resistive load to short circuit
- Short circuit to 200mA resistive load
- Short circuit continuous

Capture the voltage, and current of the rail under test and the voltage of VBATT. Validate the Comms does not misoperate in any way.

3.10.6.2 Test Data

To each regulator output, apply no load to 200mA resistive load			
Regulator	Capture voltage and current of the rail and the voltage of VBATT	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply 200mA resistive load to no load			
Regulator	Capture voltage and current of the rail and the voltage of VBATT	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply no load to 10 μ F MLCC			
Regulator	Capture voltage and current of the rail and the voltage of VBATT	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply 200mA resistive load and add 10μF MLCC			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply no load to short circuit			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply short circuit to no load			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply 200mA resistive load to short circuit			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply short circuit to 200mA resistive load			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

To each regulator output, apply short circuit continuous load			
Regulator	Capture voltage and current of the rail and the voltage of <i>VBATT</i>	Passing Criteria	Pass / Fail
5.0V		No misoperation	
9.0V		No misoperation	

3.10.6.3 Test Notes

Delete me if no notes are required.

3.11 Low Drop-Out Regulators

Results: Pass / Fail

This test evaluates the circuit described in Low Drop-Out Regulators. More information on measuring noise/ripple as well as using an oscilloscope can be found on the Electrical Systems Team page of the Wiki under Tutorials and Resources

3.11.1 Output Voltage

3.11.1.1 Test Instructions

Apply 3.7V to VBATT. Measure the voltage of the 3.3V-0 and 5.0V-0 LDO regulators under no load and under an 50mA resistive load.

Note: Measure the DC component with $f < 0.1\text{Hz}$

3.11.1.2 Test Data

Measure the voltage of the 3.3V-0 and 5.0V-0 LDO regulators under no load and under a 50mA resistive load				
Regulator	No Load Voltage	50mA Load Voltage	Passing Criteria	Pass / Fail
3.3V-0			$3.25V < V < 3.35V$	
5.0V-0			$4.95V < V < 5.05V$	

3.11.1.3 Test Notes

Delete me if no notes are required.

3.11.2 Output Ripple

3.11.2.1 Test Instructions

Apply 3.7V to VBATT. Measure the ripple of the 3.3V-0 and 5.0V-0 LDO regulators whilst under a 50mA resistive load.

Note: Measure the AC component with $0.1\text{Hz} < f < 100\text{Hz}$

3.11.2.2 Test Data

Measure the ripple of the 3.3V-0 and 5.0V-0 LDO regulators whilst under a 50mA resistive load.				
Regulator	Capture the ripple		Passing Criteria	Pass / Fail
3.3V-0			$ V_{\text{ripple}} < 25\text{mV}$	
5.0V-0			$ V_{\text{ripple}} < 45\text{mV}$	

3.11.2.3 Test Notes

Delete me if no notes are required.

3.11.3 Output Noise

3.11.3.1 Test Instructions

Apply 3.7V to VBATT. Measure the noise of the 3.3V-0 and 5.0V-0 LDO regulators whilst under a 50mA resistive load.

Note: Measure the AC component with $100\text{Hz} < f$

3.11.3.2 Test Data

Measure the noise of the 3.3V-0 and 5.0V-0 LDO regulators whilst under a 50mA resistive load.			
Regulator	Capture the noise	Passing Criteria	Pass / Fail
3.3V-0		$ V_{noise} < 50\text{mV}$	
5.0V-0		$ V_{noise} < 90\text{mV}$	

3.11.3.3 Test Notes

Delete me if no notes are required.

3.12 RF Clock Generators

Results: Pass / Fail

This test evaluates the circuit described in RF Clock Generators.

3.12.1 Reference Clock Supply

3.12.1.1 Test Instructions

Measure the voltage of each reference clock's supply. Ensure the voltage, including noise and ripple, is $3.3\text{V} \pm 0.5\%$.

3.12.1.2 Test Data

Measure the voltage of each reference clock's supply.			
RF Chain	Capture the voltage	Passing Criteria	Pass / Fail
700mm Uplink		$3.28\text{V} < V < 3.32\text{V}$	
700mm Downlink		$3.28\text{V} < V < 3.32\text{V}$	
230mm Downlink		$3.28\text{V} < V < 3.32\text{V}$	

3.12.1.3 Test Notes

Delete me if no notes are required.

3.12.2 Reference Clock Frequency

3.12.2.1 Test Instructions

Measure the frequency of each reference clock. Ensure the frequency is $20\text{MHz} \pm 5\text{ppm}$.

3.12.2.2 Test Data

Measure the frequency of each reference clock output			
RF Chain	Capture the oscillator output	Passing Criteria	Pass / Fail
700mm Uplink		$f = 20MHz \pm 5ppm$	
700mm Downlink		$f = 20MHz \pm 5ppm$	
230mm Downlink		$f = 20MHz \pm 5ppm$	

3.12.2.3 Test Notes

Delete me if no notes are required.

3.12.3 Output Frequency**3.12.3.1 Test Instructions**

Configure each generator to output its frequency as follows. Use a spectrum analyzer to measure the output. Ensure the frequency is within 10ppm and bandwidth is less than 200ppm.

- 700mm Uplink: 880MHz
- 700mm Downlink: 440MHz
- 230mm Downlink: 1.25GHz

Note: Measure the bandwidth at the $-3dB$ point

3.12.3.2 Test Data

Measure the frequency of each generator output with a spectrum analyzer			
RF Chain	Capture the generator output	Passing Criteria	Pass / Fail
700mm Uplink		$f = 880MHz \pm 10ppm$ $B < 176kHz$	
700mm Downlink		$f = 440MHz \pm 10ppm$ $B < 88kHz$	
230mm Downlink		$f = 1.25GHz \pm 10ppm$ $B < 250kHz$	

3.12.3.3 Test Notes

Delete me if no notes are required.

3.13 Differential Drivers

Results: Pass / Fail

This test evaluates the circuit described in Differential Drivers.

3.13.1 Test Instructions

Have the μ Controller generate a square wave on each modulator input with a frequency of 250kHz. Validate the waveform and voltage levels.

3.13.2 Test Data

Have the μ Controller generate a square wave on each modulator input with a frequency of 250kHz.			
Signal	Capture the single ended and differential signals	Passing Criteria	Pass / Fail
MOD_230_ID		$V = 1.2V \pm 0.5V$ Signal Integrity	
MOD_230_QD		$V = 1.2V \pm 0.5V$ Signal Integrity	
MOD_700_ID		$V = 0.7V \pm 0.3V$ Signal Integrity	
MOD_700_QD		$V = 0.7V \pm 0.3V$ Signal Integrity	

3.13.3 Test Notes

Delete me if no notes are required.

3.14 Power Amplifier Bias

Results: Pass / Fail

This test evaluates the circuit described in Power Amplifiers.

3.14.1 Test Instructions

Have the μ Controller sweep each power amplifier bias from 0% to 100% duty cycle. Validate the output sweeps from $-3.3V$ to $0V$.

3.14.2 Test Data

Have the μ Controller sweep each power amplifier bias from 0% to 100% duty cycle. Validate the output sweeps from $-3.3V$ to $0V$.					
RF Chain	Duty Cycle			Passing Criteria	Pass / Fail
	0%	50%	100%		
230mm				$V(0 \rightarrow 1) = -3.3V \rightarrow 0V$	
700mm				$V(0 \rightarrow 1) = -3.3V \rightarrow 0V$	

3.14.3 Test Notes

Delete me if no notes are required.

3.15 RF Chain - 230mm Downlink

Results: Pass / Fail

This test evaluates the circuit described in RF Modulators, Low Noise Amplifier, and Power Amplifiers.

3.15.1 Test Instructions

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 500kbps. Validate the following parameters:

- Power output of 1W when power amplifier bias is set to maximum
- Spectral bandwidth of less than 250kHz

- Distinct separation of symbols

3.15.2 Test Data

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 500kbps on the 230mm radio.			
Parameter	Value (Scope or Spectrum Analyzer Capture)	Passing Criteria	Pass / Fail
Output Power		$P = 1W \pm 0.2W$	
Spectral Bandwidth		$B < 250kHz$	

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 500kbps on the 230mm radio. Use an SDR to demodulate into symbols			
Capture the I/Q signals (waveforms and constellation)		Passing Criteria	Pass / Fail
		Distinct Symbols	

3.15.3 Test Notes

Delete me if no notes are required.

3.16 RF Chain - 700mm Downlink

Results: Pass / Fail

This test evaluates the circuit described in RF Modulators, Low Noise Amplifier, and Power Amplifiers.

3.16.1 Isolation Switch

3.16.1.1 Test Instructions

Have the μ Controller gradually increase the power output of the 700mm downlink radio while the RF switch is set to downlink. Measure the power on the 700mm uplink radio input. Ensure this power does not exceed 0dBm.

3.16.1.2 Test Data

Have the μ Controller gradually increase the power output of the 700mm downlink radio while the RF switch is set to downlink. Measure the power on the 700mm uplink radio input. Ensure this power does not exceed 0dBm.		
Max power	Passing Criteria	Pass / Fail
	$P < 0dBm$	

3.16.1.3 Test Notes

Delete me if no notes are required

3.16.2 Digital Modulation

3.16.2.1 Test Instructions

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps on the 700mm radio. Validate the following parameters:

- Power output of 1W when power amplifier bias is set to maximum
- Spectral bandwidth of less than 25kHz
- Distinct separation of symbols

3.16.2.2 Test Data

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps on the 700mm radio.			
Parameter	Value (Scope or Spectrum Analyzer Capture)	Passing Criteria	Pass / Fail
Output Power		$P = 1W \pm 0.2W$	
Spectral Bandwidth		$B < 25kHz$	

Have the μ Controller generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps on the 700mm radio. Use an SDR to demodulate into symbols		
Capture the I/Q signals (waveforms and constellation)	Passing Criteria	Pass / Fail
	Distinct Symbols	

3.16.2.3 Test Notes

Delete me if no notes are required.

3.16.3 Analog Modulation

3.16.3.1 Test Instructions

Have the μ Controller generate an amplitude modulated audio signal on the 700mm radio. Validate the following parameters:

- Power output of 1W when power amplifier bias is set to maximum
- Spectral bandwidth of less than 20kHz
- Recognizable demodulated audio

3.16.3.2 Test Data

Have the μ Controller generate an amplitude modulated audio signal on the 700mm radio.			
Parameter	Value (Scope or Spectrum Analyzer Capture)	Passing Criteria	Pass / Fail
Output Power		$P = 1W \pm 0.2W$	

Have the μ Controller generate an amplitude modulated audio signal on the 700mm radio.			
Parameter	Value (Scope or Spectrum Analyzer Capture)	Passing Criteria	Pass / Fail
Spectral Bandwidth		$B < 20kHz$	

Have the μ Controller generate an amplitude modulated audio signal on the 700mm radio. Use an SDR to demodulate into audio.			
Capture the I/Q signals (waveforms)		Passing Criteria	Pass / Fail
		Recognizable audio	

3.16.3.3 Test Notes

Delete me if no notes are required.

3.17 RF Chain - 700mm Uplink

Results: Pass / Fail

This test evaluates the circuit described in RF Demodulator, and Low Noise Amplifier.

3.17.1 Test Instructions

Have a radio generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps to transmit to the 700mm radio with a received power of $-150dBm$. Validate the following parameters:

- Signal to noise ratio (SNR) $> 30dBm$
- Output voltage of $1.65V \pm 1V$
- Distinct separation of symbols

3.17.2 Test Data

Have a radio generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps to transmit to the 700mm radio with a received power of $-150dBm$.			
Parameter or Signal	Value (Scope or Spectrum Analyzer Capture)	Passing Criteria	Pass / Fail
SNR		$SNR > 30dBm$	
DEMOD_ID		$V = 1.65V \pm 1V$	
DEMOD_QD		$V = 1.65V \pm 1V$	

Have a radio generate a QPSK modulated signal with pattern 00 01 11 10 with a data rate of 50kbps to transmit to the 700mm radio with a received power of $-150dBm$.			
Capture the I/Q signals (waveforms and constellation)		Passing Criteria	Pass / Fail
		Distinct Symbols	

3.17.3 Test Notes

Delete me if no notes are required.